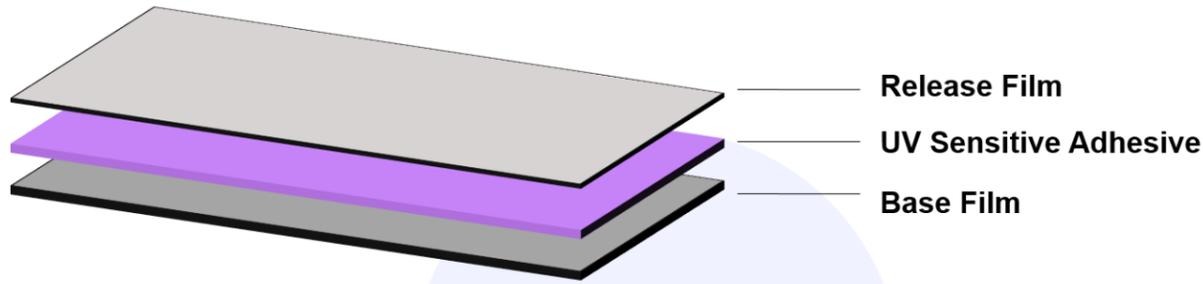


### UV Tape Application

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- Chip grinding process
- Chip dicing process
- Chip flipping process
- Ceramics cutting process
- Use for temporary fixed purpose



### Feature

- Make for semiconductor device 、 electronic component 、 optoelectronics 、 LED...etc. cutting or grinding process.
- Qualities have been certificated by international leading companies.
- Stabilities can compare to Japan leading companies.
- Special adhesive with excellent adhesion ， avoid chip loss when cutting.
- Special structure design ， decrease impacts for blade lifetime.
- Food-grade base material ， non-toxic ， soft 、 smooth and good for pick up.
- After UV irradiation ， adhesion decreased ， no any residue.
- Rapid reaction time for UV irradiation ， it can substantially increase efficiency in your manufacturing process.

Model	Process	Base film material	Color	Characteristic
E-22HA	chip/glass cutting (FE)	POF(Polyolefin)	Milky white	Easy pick up
E-26PA				Avoid side chipping
E-27EA				For tiny chip cutting
VC-80A		PVC (Poly vinyl chloride)	Blue	Excellent stretchability
E-140A	Package saw (BE)	POF(Polyolefin)	Milky white	a. Less cutting debris
E-150A				b. Less adhesive residue
E-180A				c. Less impact to marking quality
E-22ZH				d. Excellent UV release ability
E-288A				

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